



原厂直销专员钱生电话：15919711751 微信同步 Q Q:641226513 **ASC100N1700MT4**

1700V N-Channel MOSFET

Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

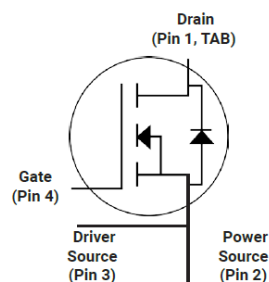
Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Simple to drive with Standard Gate Drive
- 100% avalanche tested
- Maximum junction temperature of 150°C
- ROHS Compliant



Application

- EV Charging
- DC-AC Inverters
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives



Part Number	Marking	Package	Packaging
ASC100N1700MT4	ASC100N1700MT4	TO-247	Tube



ASC100N1700MT4

Absolute Maximum Ratings($T_c=25^\circ\text{C}$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	1700	V
I_D	Drain Current(continuous)at $T_c=25^\circ\text{C}$	100	A
I_D	Drain Current(continuous)at $T_c=100^\circ\text{C}$	68	A
I_{DM}	Drain Current (pulsed)	200	A
V_{GS}	Gate-Source Voltage	-10/+25	V
P_D	Power Dissipation $T_c = 25^\circ\text{C}$	420	W
T_J, T_{stg}	Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Electrical Characteristics($T_J = 25^\circ\text{C}$ unless otherwise specified)

Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	1700			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=1700\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$			100	μA
I_{GSS}	Gate-body Leakage Current	$V_{DS}=0\text{V}; V_{GS}=-10\text{ to }20\text{V}$			250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=20\text{mA}$	2		4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=20\text{V}, I_D=50\text{A}$		20	30	$\text{m}\Omega$
R_G	Gate Resistance	$V_{GS}=0\text{V}, f=1\text{MHz}$		3		Ω

Typical Performance-Dynamic

C_{iss}	Input Capacitance	$V_{DS}=800\text{V}, f=1000\text{KHz}, V_{GS}=0\text{V}$	4850		pF
C_{oss}	Output Capacitance		128		pF
C_{rss}	Reverse Transfer Capacitance		18		pF
Q_g	Total Gate Charge	$V_{DS}=800\text{V}, I_D=50\text{A}, V_{GS}=-4\sim 20\text{V}$	160		nC
Q_{gs}	Gate-source Charge		56		nC
Q_{gd}	Gate-Drain Charge		46		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=800\text{V}, I_D=50\text{A}, V_{GS}=-4\text{V}\sim 20\text{V}, R_G=0\Omega,$	146		ns
t_r	Rise Time		28		ns
$t_{d(off)}$	Turn-off Delay Time		77		ns
t_f	Fall Time		22		ns



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Typical Performance-Reverse Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{FSD}	Forward Voltage	$V_{GS}=0V, I_F=30A, T_J=25^{\circ}C$	3		6	V
		$V_{GS}=0V, I_F=30A, T_J=150^{\circ}C$	3		6	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_F=30A,$ $V_R=800V,$ $di/dt=100A/\mu s$		92		ns
Q_{rr}	Reverse Recovery Charge			780		nC
I_{rrm}	Peak Reverse Recovery Current			19		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.3	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Case	40	$^{\circ}C/W$

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of $T_J(\max)=150^{\circ}C$

● Electrical characteristic curves

Fig.1 Typical Output Characteristics(I)

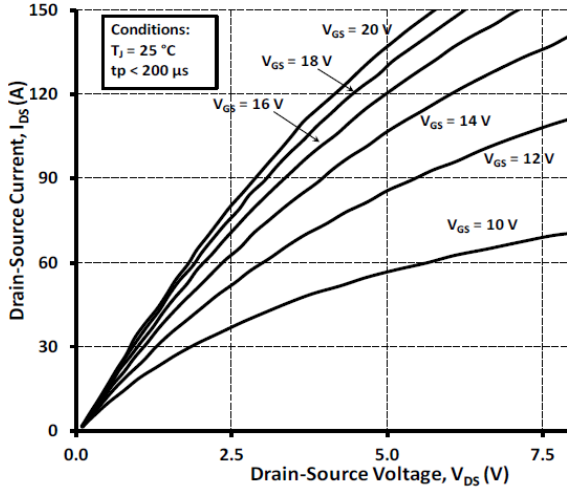


Fig.2 Typical Output Characteristics(II)

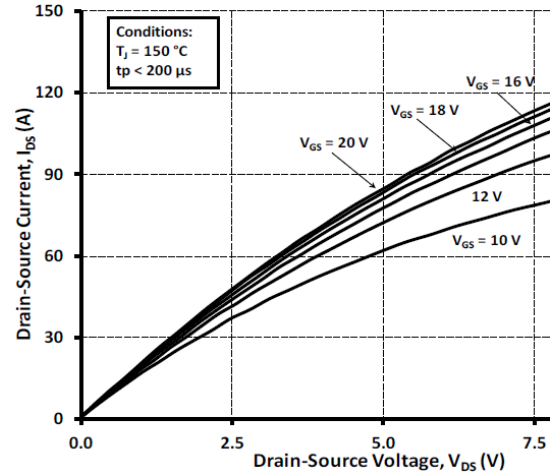


Figure 3. Normalized On-Resistance vs. T_j

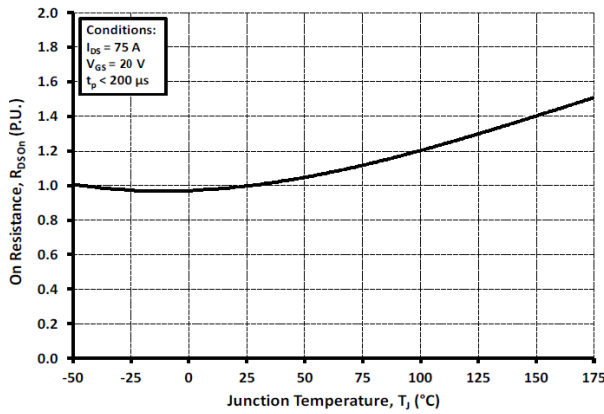


Figure 4. On-Resistance vs. Drain Current

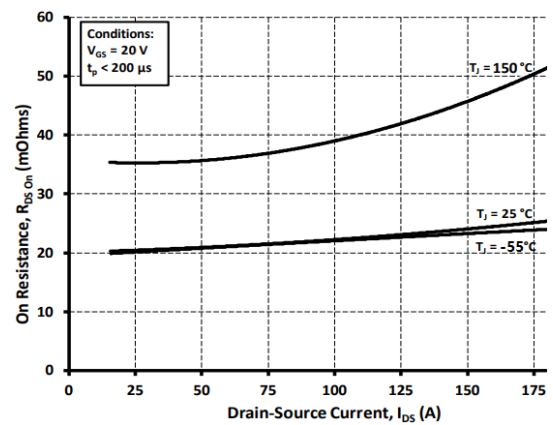


Figure 5. Transfer Characteristic for Various T_j

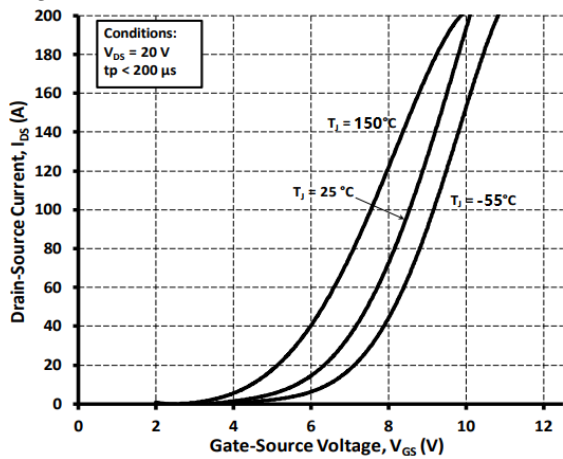


Figure 6. Body Diode Characteristic

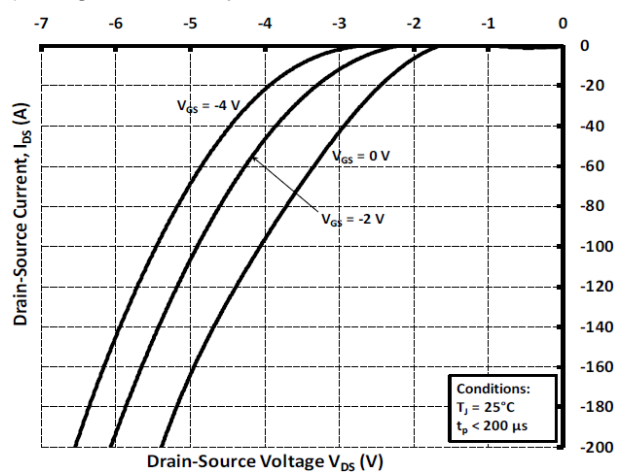


Figure 7. Threshold Voltage vs. T_j

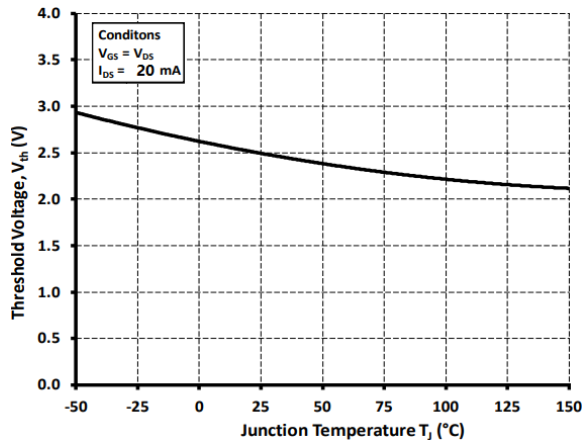


Figure 8. Gate Charge Characteristics

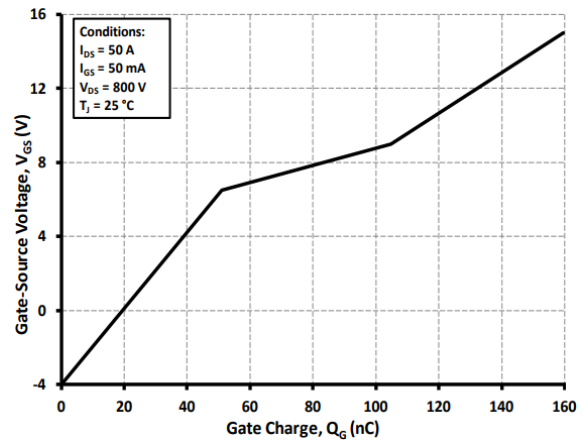


Figure 9. Output Capacitor Stored Energy

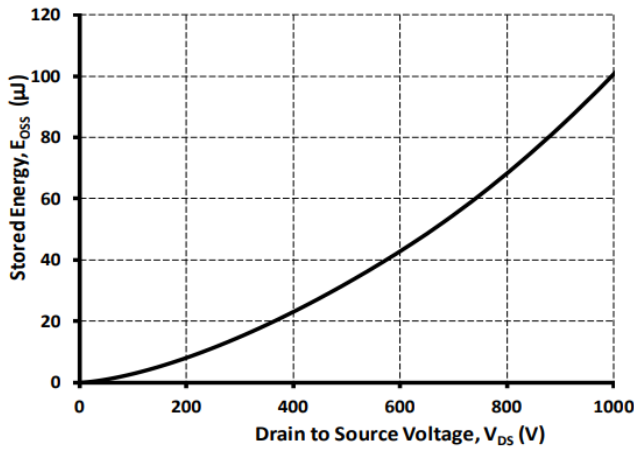


Figure 10. Capacitances vs. V_{DS}

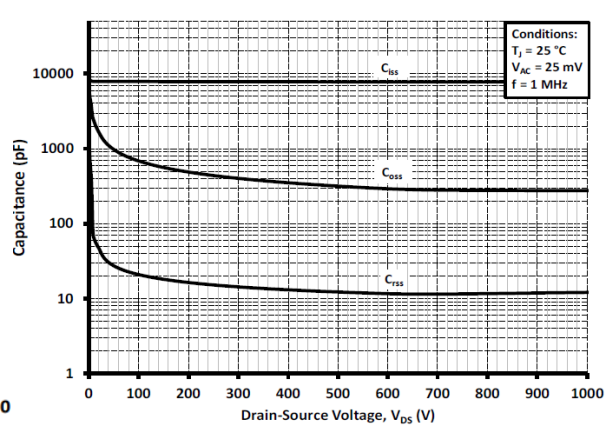


Figure 11. Continuous Drain Current vs. T_c

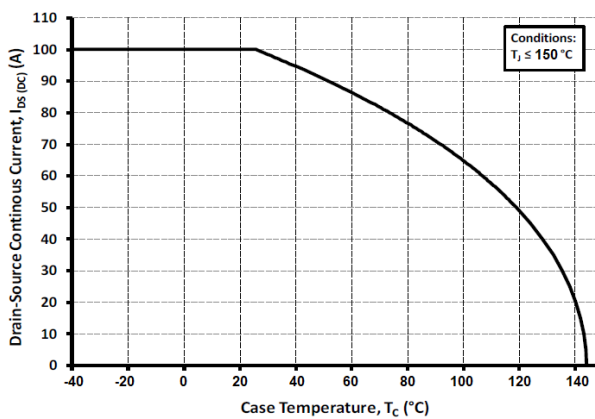


Figure 12. Maximum Power vs. T_c

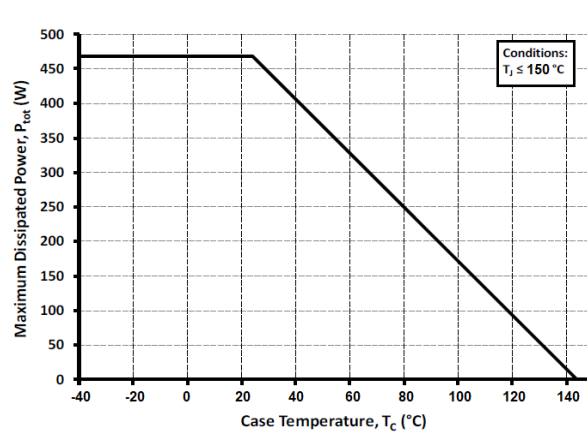


Figure 13. Transient Thermal Impedance

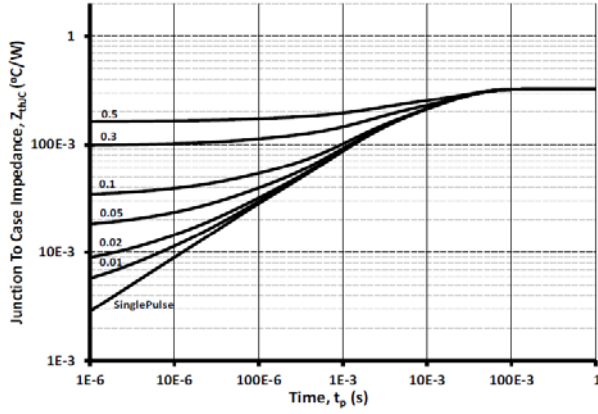


Figure 14. Safe Operating Area

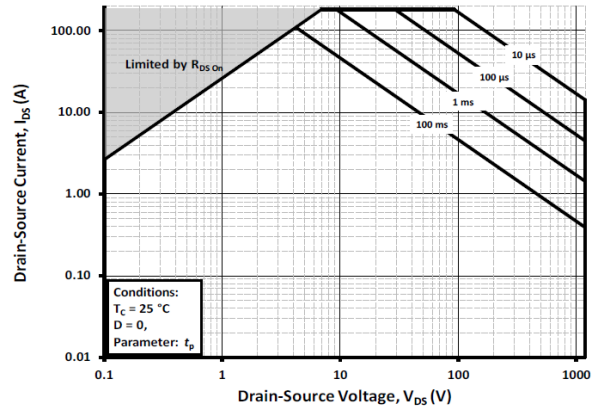


Figure 15. Switching Energy vs. RG(ext)

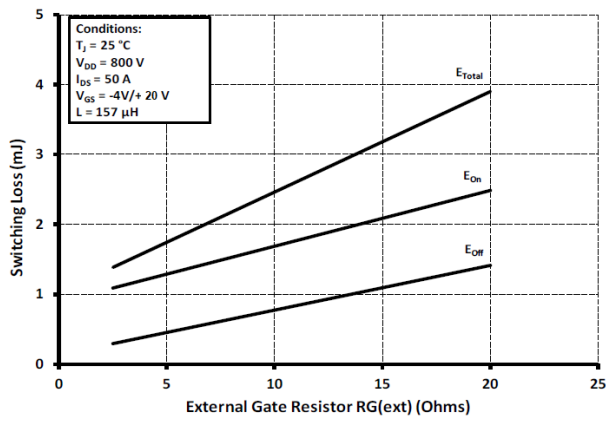
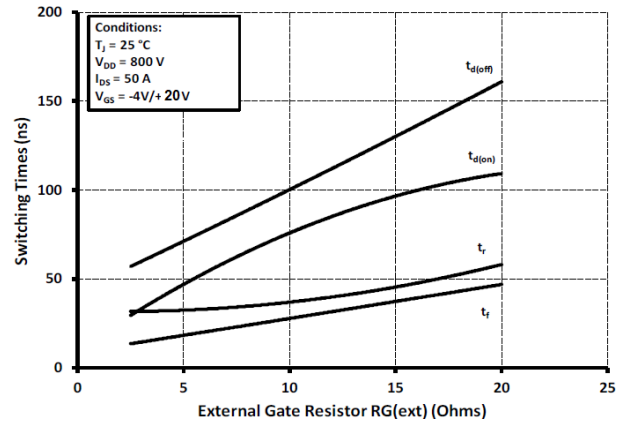
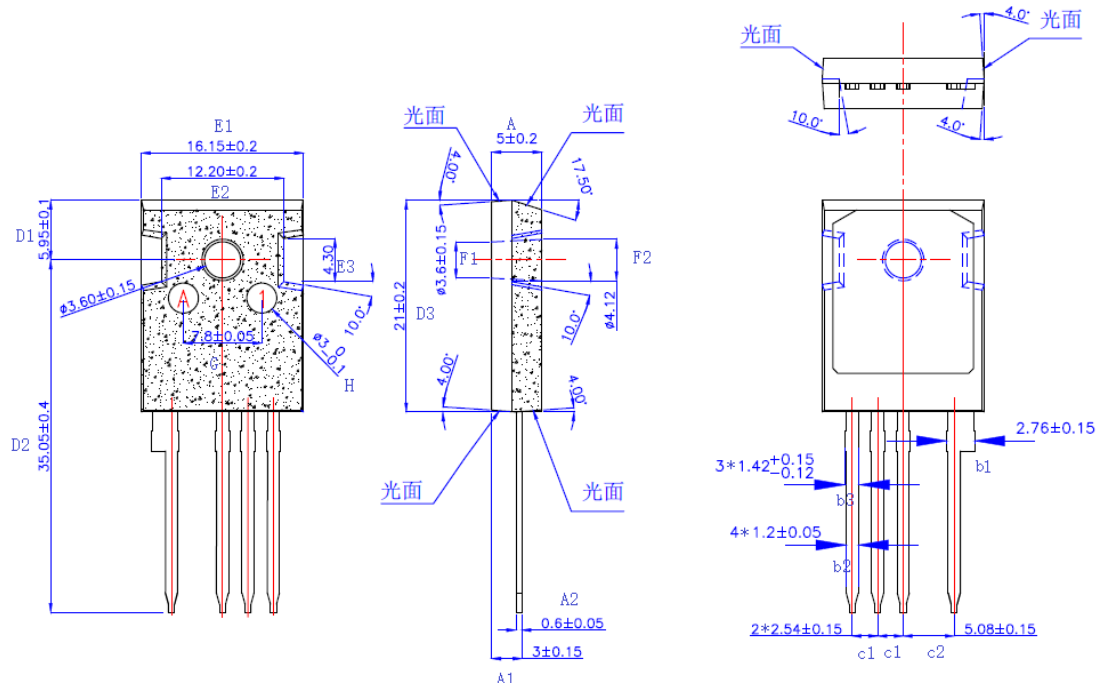


Figure 16. Switching Times vs. RG(ext)



Package Drawing:

Dimensions (UNIT: mm)

SYM	MILLIMETERS		SYM	MILLIMETERS	
	MIN	MAX		MIN	MAX
A	4.98	5.02	D2	34.65	35.45
A1	2.85	3.15	D3	20.80	21.20
A2	0.55	0.65	E1	15.95	16.35
b1	2.61	2.91	E2	12.00	12.40
b2	1.15	1.25	F1	3.45	3.75
b3	1.30	1.57	F2	4.12	4.12
c1	2.39	2.69	G	7.75	7.85
c2	4.93	5.23	H	2.90	3.10
D1	5.85	6.05			